



Material Content Data Sheet



Sales Product Name	BTS426L1 E3062A	Issued	14. May 2021
MA#	MA003365850		
Package	PG-TO263-5-2	Weight*	1497.86 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.039	0.34	0.34	3364	3364
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158	
	non noble metal	iron	7439-89-6	0.790	0.05		527	
	non noble metal	copper	7440-50-8	788.527	52.63	52.70	526434	527119
wire	non noble metal	aluminium	7429-90-5	1.962	0.13	0.13	1310	1310
encapsulation	organic material	carbon black	1333-86-4	6.330	0.42		4226	
	inorganic material	antimonytrioxide	1309-64-4	13.235	0.88		8836	
	plastics	brominated resin	-	14.962	1.00		9989	
	plastics	epoxy resin	-	109.335	7.30		72994	
	inorganic material	silicondioxide	60676-86-0	431.585	28.81	38.41	288133	384178
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6903	6903
plating	inorganic material	phosphorus	7723-14-0	0.008			5	
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2284	2289
solder	non noble metal	tin	7440-31-5	0.080	0.01		54	
	noble metal	silver	7440-22-4	0.100	0.01		67	
	non noble metal	lead	7439-92-1	3.830	0.26	0.28	2557	2678
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			22	
	non noble metal	iron	7439-89-6	0.108	0.01		72	
	non noble metal	copper	7440-50-8	107.943	7.21	7.22	72065	72159
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com